Input Voltage = 30.4Vin to 33.6Vin

*NOTES:
1. Cx1 is a bulk capacitor that was used to dampen the input supply. When building this design please ensure to use input bulk capacitor(s) that can handle a total of 7.5Arms.
2. All components with an "x" suffix are components that were not in the original PCB design (i.e. do not have pads on the PCB) and were kluged into the circuit.
3. C6 can be replaced by a 50V rated capacitor (still needs to be a ceramic, 1uF, X7R rated device).
4. Built on the PMP9280 Rev1 PCB.
PCB Assembly

PCB LOGO

Texas Instruments

Label Table

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Assembly Note

ZZ1

This Assembly Note is for PCB labels only.

ZZ2

ESD Sensitive, ESD precautions shall be observed.

ZZ3

These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4

These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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